



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Wolfgang Ehrfeld, et al.

Examiner:

Serial No.: 10/009,184

Group Art Unit:

Filed:

Date: May 14, 2002

For: **"STORAGE MAGAZINE FOR MICROSTRUCTURED MOLDED PARTS
AND FABRICATION PROCEDURE"**

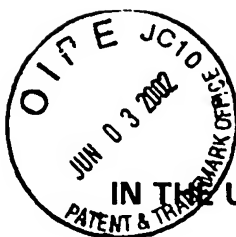
Commissioner of Patents and Trademarks
Washington, D.C. 20231

INFORMATION DISCLOSURE STATEMENT

Sir:

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TC 1700

The present invention describes a procedure for replicative fabrication and packaging of at least one microstructured molded part as one magazine/molded part composite as well as a magazine with at least one microstructured molded part as one magazine/molded part composite. The first step covers fabrication of at least one microstructured molded part using an initially closed tool which consists of at least one first and one second tool half. In the second step, both tool halves are opened, whereby the molded part remains in the first tool half. In the third step, at least the second tool half is replaced with at least one additional tool half. In the fourth step, the replicative fabrication of the magazine is carried out using the first tool half containing the molded part and the additional tool half. Finally in the fifth step, magazine and molded part are demolded simultaneously as one magazine/molded part composite. Under the invention, either the magazine or the microcomponents can be fabricated first depending on the final design of the microcomponent and magazine. This procedure, which preferably uses a 2-



JG13 Rec'd PCT/PTO 0.3 JUN 2002

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CERTIFICATE OF MAILING

Sir:

The undersigned hereby certifies that the attached **INFORMATION DISCLOSURE STATEMENT, PTO FORM-1449 AND FIVE REFERENCES** were mailed to the Assistant Commissioner for Patents, Washington, D.C. 20231, with sufficient first-class postage, no special handling, on May 14, 2002, before 5:00 PM, thereby ensuring that such document(s) will be in the hands of the U.S. Postal Service by the close of business this day.

The Commissioner is hereby authorized to charge any fees which might be required or credit any overpayment of fees with regard to the attached document(s) to Account No. **08-3150**.

Respectfully submitted,

HUDAK & SHUNK CO., L.P.A.

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Enclosures: Return Postcard
Certificate of Mailing
Information Disclosure Statement, Form PTO-1449, 5 references

(1 732)

component injection molding process, allows the direct fabrication of several molded parts or microcomponents and their magazine packaging as one magazine/molded part composite without any after-treatment requirement, whereby different physical heights are fabricated for the magazine and microcomponents. Since the magazine connects the microcomponents only at parts of the side, bottom or face surfaces, a gripper can be used for very precise, fully automated mounting of the microcomponent.

As authorized and encouraged under 37 C.F.R. §1.97-1.99, applicant hereby cites as a means of complying with the duty of disclosure set forth in 37 C.F.R. §1.56, the following patents and/or documents, copies enclosed, which the Examiner should consider with respect to the above-identified United States Patent Application:

FOREIGN DOCUMENTS		
PATENT/DOCUMENT NO.	DATE	COUNTRY
0 517 613	December 9, 1992	EP
197 09 136	September 10, 1998	DE
198 42 456	April 22, 1999	DE
WO 98/39230	September 11, 1998	WIPO
WO 98/39501	September 11, 1998	WIPO

Copies of the publications are included for the express purpose of providing the Patent and Trademark Office with an ample opportunity to evaluate the same and to arrive at an independent assessment of their materiality, if any, with regard to the examination of the application.

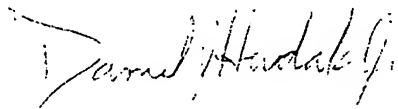
In reviewing the enclosed copies of the above publications, the Examiner is requested to ignore any underscoring or highlighting which may appear because such

markings may or may not have any relationship to the subject matter of the above-identified application. The copies being submitted with this Information Disclosure Statement are the best copies available at this time.

An examination of the present application considering the above documents is requested.

Respectfully submitted,

HUDAK & SHUNK CO., L.P.A.

A handwritten signature in dark ink, appearing to read "Daniel J. Hudak Jr.", is written over a horizontal line.

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